

Technical data sheet of Hitachi Chemical Epoxy molding compound

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(The contents of this data sheet are based on the experiments conducted by Hitachi Chemical, and do not represent a guarantee of the values for each property.)

Table 1. Composition

Items	Unit	CEL-9220HF10
Epoxy resin	-	LMW + Biphenyl
Hardener	-	LWA
Flame retardant	-	No FR
Filler content	wt %	90
Filler shape	-	Spherical

Table 2. Moldability

Items	Unit	Value
Spiral Flow (175degC)	cm	91
Gelation time (175degC)	sec	30
Hot hardness	Shore-D	89
Viscosity(175degC)	Pa.s	24.9

Table 3. Physical property

Items	Unit	Value	
Tg	degC	124	
CTE	Alpha 1	ppm/degC	8
	Alpha 2	ppm/degC	31
Flexural modulus at RT	GN/m ²	27	
Flexural strength at RT	MN/m ²	166	
Specific gravity	-	2.02	
Volume resistivity	at 150 degC	E+12 ohm.cm	11.5
Mold shrinkage	%	0.15	
Thermal conductivity	W/mk	0.9	
Flammability	UL-94	V-0	
Dielectric constant	at 1MHz	-	3.1
Dissipation factor	at 1MHz	%	1.1

Table 4. Chemical property

Items	Unit	Value
EC	uS/cm	32
pH	-	7.0
Cl ⁻	ppm	4
Na ⁺	ppm	2